

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.44952	100.0	4.8
			Subtotal	0.44952	100	4.8
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03755	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01127	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03755	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.46691	99.77	400.0777
			Subtotal	37.55328	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84543	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.92799	10.0	63.3
	Filler	Silica fused	60676-86-0	50.38789	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11856	0.2	1.266
			Subtotal	59.27987	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34123	100.0	25
			Subtotal	2.34123	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.08579	100.0	0.91609
			Subtotal	0.08579	100	0.91609
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00581	2.0	0.062
	Lead alloy	Silver (Ag)	7440-22-4	0.00726	2.5	0.0775
	Lead alloy	Lead (Pb)	7439-92-1	0.27725	95.5	2.9605
			Subtotal	0.29032	100	3.1
			Total	100.00001	100	1067.81609

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